



- (51) **International Patent Classification:**
C09J 163/00 (2006.01) *C09J 7/02* (2006.01)
C09J 9/02 (2006.01)
- (21) **International Application Number:**
PCT/CN2012/082466
- (22) **International Filing Date:**
29 September 2012 (29.09.2012)
- (25) **Filing Language:** English
- (26) **Publication Language:** English
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- (81) **Designated States** (*unless otherwise indicated, for every kind of national protection available*): AE, AG, AL, AM, AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ, CA, CH, CL, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS, RU, RW, SC, SD, SE, SG, SK, SL, SM, ST, SV, SY, TH, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW.
- (84) **Designated States** (*unless otherwise indicated, for every kind of regional protection available*): ARIPO (BW, GH, GM, KE, LR, LS, MW, MZ, NA, RW, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT, LU, LV, MC, MK, MT, NL, NO, PL, PT, RO, RS, SE, SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:
— with international search report (Art. 21(3))

(54) **Title:** ADHESIVE COMPOSITION AND ADHESIVE TAPE

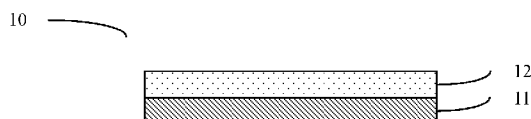


Figure 1

(57) **Abstract:** The present invention provides a thermally conductive adhesive composition, based on the total weight of the composition, comprising: (a) 5-70% by weight of an epoxy component; (b) 5-60% by weight of thermally conductive material; (c) 0.001-10% by weight of a photoinitiator; (d) 0-40% by weight of a thermoplastic polymer; (e) 0-50% by weight of a hydroxyl-functional component; and (f) 0-50% by weight of a halogen-free flame retardant. The present invention further provides a thermally conductive adhesive tape comprising the adhesive composition.

